

Thermal RC network (Foster)

SPICE thermal model

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R _{th(j-mb)}	thermal resistance from junction to mounting base		-	-	2.75	K/W
	Cth ₁	1.598E-05 F		Ą	4	
	Cth ₂	1.754E-04 F		_	t j	
	Cth ₃	1.300E-04 F				
	Cth ₄	8.034E-03 F			$\begin{bmatrix} \\ Rth_1 \\ \blacksquare \\ Cth_1 \end{bmatrix}$	
	Cth ₅	8.275E-04 F				
	Cth ₆	6.710E-03 F				
	Cth ₇	7.777E-02 F		Г	ᠳ᠊ᠲ	
	Cth ₈	8.620E+01 F			$\int Rth_2 = Cth_2$	•
	Rth ₁	3.930Ε-03 Ω				
	Rth ₂	6.913E-03 Ω		Г	$\neg \neg \neg$	
	Rth ₃	4.368E-02 Ω			Rth3 📥 Cth3	5
	Rth ₄	1.751E-02 Ω			╧╺	
	Rth₅	1.045E+00 Ω				
	Rth ₆	1.260E+00 Ω				l.
	Rth ₇	3.643E-01 Ω				•
	Rth ₈	3.262Ε-03 Ω	((P)		
				\int		;
					╧┓	
				Г	5	
					$\int Rth_6 = Cth_6$;
					Rth7 $= Cth_7$,
					╧╺┓┘	
Part:	BUK9M10-30E			ſ		2
Date:	3/3/2016					•
Nodel Rth	2.75 K/W					
				\downarrow	t _{amb}	
					001aal768	}

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